

PATENT ASSIGNMENT

Electronic Version v07
 Stylesheet Version v02

SUBMISSION TYPE:		NEW ASSIGNMENT		APPLICATION NUMBER 10/707803	
NATURE OF CONVEYANCE:		ASSIGNMENT OF ASSIGNOR'S INTEREST			
CONVEYING PARTY DATA					
Name		Execution Date			
Chao-Cheng Lee		2004-01-13			
Chia-Jun Chang		2004-01-13			
RECEIVING PARTY DATA					
Name	Street Address	Internal Address	City	State/Country	Postal Code
Realtek Semiconductor Corp.	2 Industry E. Rd. IX, Science-Based Industrial	Park	Hsin-Chu Hsien	TAIWAN	
CORRESPONDENCE DATA					
FAX NUMBER: 886229295950 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> When the customer number has been provided, the Office of Public Records will obtain the correspondence data from the official record on file at the USPTO. CUSTOMER NUMBER: 027765					
NAME OF PERSON SIGNING:		WINSTON HSU			
DATE SIGNED:		2004-01-13			
Total Attachments: 2 source=REAP0003ASS1.tif source=REAP0003ASS2.tif					

CH \$40.00 500801 10707803

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNORS (Inventors):

Name: Chao-Cheng Lee Nationality: R.O.C.

Address: No. 61-1, Lane 2, Shin-Sheng Rd., Jung-Li City, Tao-Yuan Hsien, Taiwan, R.O.C.

Name: Chia-Jun Chang Nationality: R.O.C.

Address: 7F, No. 1, Alley 22, Lane 66, Sec. 5, Nan-Jing E. Rd, Taipei City, Taiwan, R.O.C.

Hereby sells, assigns and transfers to **Realtek Semiconductor Corp.**
(hereinafter 'Assignee'), of (Assignee address)

2 Industry E. Rd. IX, Science-Based Industrial Park
, Hsin-Chu Hsien, Taiwan, R.O.C.

, and the successors assigns and legal representatives of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"AMPLIFYING CIRCUIT"

Which is found in :

- (a) _____ U.S. patent application executed on even date
- (b) _____ U.S. patent application executed on _____
- (c) _____ U.S. application serial no. _____
- (d) _____ patent no. _____ issued _____

and, in and to, all Letters Patent to be obtained for said invention by the above application or ant continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment,

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this _____ (Date of signing).

(Type name of inventor)

Signature of INVENTOR

Chao-Cheng Lee

Chao-Cheng Lee

Chia-Jun Chang

Chia-Jun Chang